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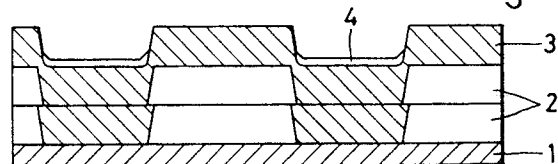
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54 **Method of making circuit board.**

57 A method of making circuit boards in which the thickness of an insulating layer (2) is held constant to ensure the fine configuration and dimensions of wiring lines and further to prevent variations in wiring intervals and wiring grounds due to unevenness of the insulating layer, thereby preventing electric characteristics from varying. The method comprising the steps of stacking an insulating layer (2) on an insulating substrate (1), and engraving the insulating layer into a wiring configuration, for example by exposure and development. A metal layer (3) is formed thereon, and photoresist is removed. This sequence of steps can be repeated as necessary obtaining a layer-structure wiring board.

Via buried metal forming

Fig.7



EP 0 572 121 A3



DOCUMENTS CONSIDERED TO BE RELEVANT			
Category	Citation of document with indication, where appropriate, of relevant passages	Relevant to claim	CLASSIFICATION OF THE APPLICATION (Int.Cl.5)
X	EP-A-0 043 458 (IBM) * page 2, line 32 - page 3, line 3 * * page 4, line 15 - line 24 * * page 9, line 4 - line 16 * * page 10, line 8 - line 16 * * page 11, line 4 - line 6 * * page 11, line 34 - page 12, line 20; figures 1-9 * ---	1,2	H05K3/00 H05K3/46 H05K3/10
X	IBM TECHNICAL DISCLOSURE BULLETIN, vol.32, no.3B, August 1989, ARMONK,NY,US page 67-68 'tft/lcd damascene scan lines' * the whole document * ---	1	
D,A	PROCEEDINGS OF THE ELECTRONIC COMPONENTS CONFERENCE, vol.34, 1984, IEEE,NEW YORK,US pages 82 - 87 K.MORIYA ET AL 'high-density multilayer interconnection with photo-sensitive polyimide dielectric and electroplating conductor' * page 82, left column, paragraph 1 * * page 82, right column, last paragraph * * page 84, right column, last paragraph; figure 1 * -----	1-3	
			TECHNICAL FIELDS SEARCHED (Int.Cl.5)
			H05K H01L
The present search report has been drawn up for all claims			
Place of search BERLIN		Date of completion of the search 1 March 1995	Examiner Alexatos, G
CATEGORY OF CITED DOCUMENTS X : particularly relevant if taken alone Y : particularly relevant if combined with another document of the same category A : technological background O : non-written disclosure P : intermediate document T : theory or principle underlying the invention E : earlier patent document, but published on, or after the filing date D : document cited in the application L : document cited for other reasons & : member of the same patent family, corresponding document			